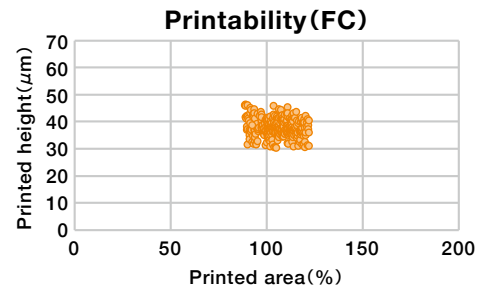
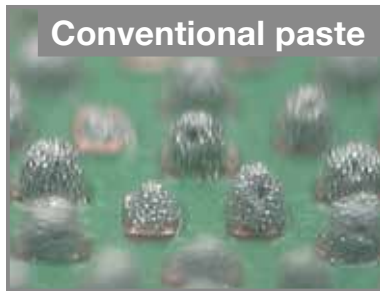
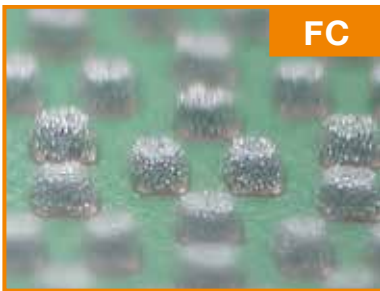


Developed 0201 chip compatible solder paste contributing to the high functionality and miniaturization of electronic devices and modules.

Characteristics

- Excellent printing at small aperture, and good wetting characteristics
- Small change of viscosity after continuous printing, can be used for a long period of time

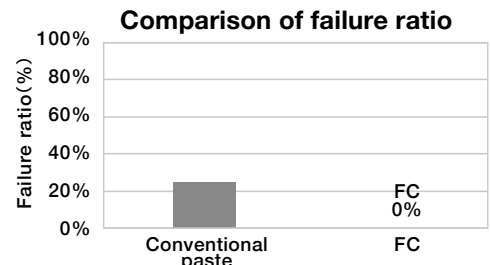
Printability



Test condition

- Mask thickness : 50μm
- Aperture size : 100×100μm
- Printing speed : 50mm/sec

Mount wettability

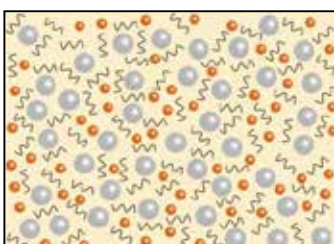


Test condition

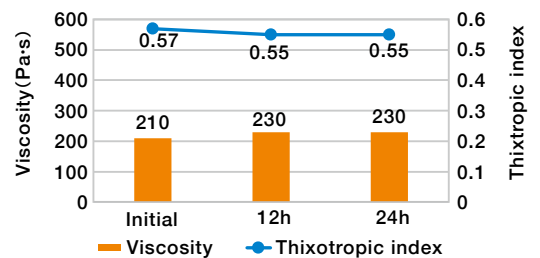
- Pre-heat : 150~180°C 90sec
- Peak temperature : 240°C
- O₂ concentration : 1,000ppm

Viscosity stability

- Suppress reaction between solder and activator by stable dispersion of flux ingredients
- ▶ Enable long time continuous printing



- Activator
- Solder powder
- ~ Stabilizer
- Flux



Test condition

- No aperture mask
- 24h continuous squeezing
- No replacement of solder paste